


# MATERIAL DECLARATION SHEET



Material Number	PTVS3-076C-SH			
Product Line	Semiconductor products			
Compliance Date	May 30 <sup>th</sup> 2014			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.239100	Bisphenol Epoxy Resin	1675-54-3	40.00	5.53	13.82
				Epoxy Resin	25085-99-8	20.00	2.76	
				Crystalline Silica	14464-46-1	23.00	3.18	
				Brominated Epoxy Resin	40039-93-8	12.00	1.66	
				Iron Oxide	51274-00-1	2.00	0.28	
				Titanium Oxide	13463-67-7	3.00	0.41	
2	Electrodes	Copper	0.801007	Copper	7440-50-8	99.10	45.88	46.30
				Silver	7440-22-4	0.40	0.19	
				Other	-	0.50	0.23	
3	Terminations	Copper	0.459942	Copper	7440-50-8	99.50	26.45	26.58
				Other	-	0.50	0.13	
4	Termination Finish	Silver	0.015281	Silver	7440-22-4	100.00	0.88	0.88
5	Chip	Silicon Die	0.076261	Silicon	7440-21-3	87.06	3.84	4.41
				Aluminium	7429-90-5	4.53	0.20	
				Nickel	7440-02-0	8.02	0.35	
				Gold	7440-57-5	0.39	0.02	
6	Die Attach	Solder	0.057154	Lead	7439-92-1	92.50	3.06	3.30
				Tin	7440-31-5	5.00	0.17	
				Silver	7440-22-4	2.50	0.08	
7	Die Coating	Silicone	0.081446	Polysiloxane	63148-62-9	22.11	1.04	4.71
				Chromium Sesquioxide	1308-38-9	5.67	0.27	
				Fumed Silica	112945-52-5	11.11	0.52	
				Filler	trade secret	61.11	2.88	
		Total Weight	1.730192					